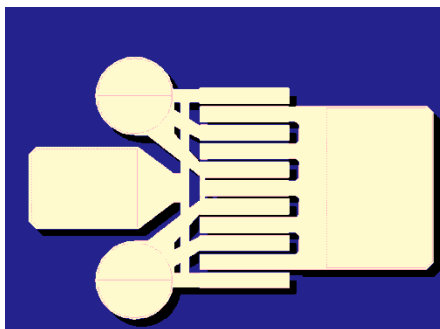
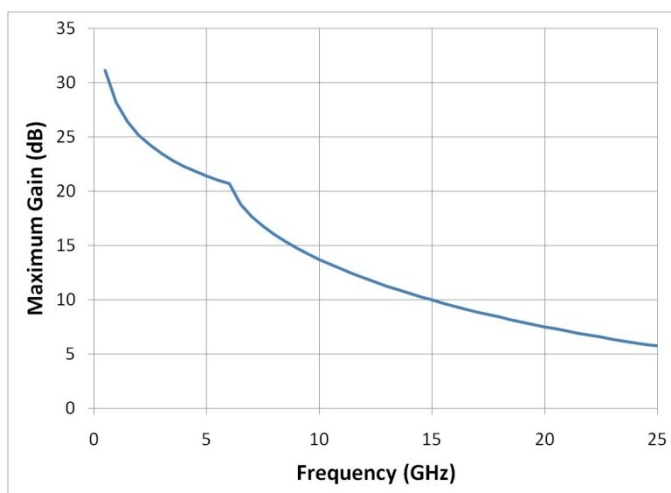


6 Watt Discrete Power GaN on SiC HEMT



Measured Performance

Bias conditions: $V_d = 30\text{ V}$, $I_{dq} = 125\text{ mA}$, $V_g = -3.6\text{ V}$ Typical



Key Features

- Frequency Range: DC - 18 GHz
- 38 dBm Nominal P_{sat}
- 55% Maximum PAE
- 10 dB Nominal Power Gain at 10GHz
- Bias: $V_d = 28 - 35\text{ V}$, $I_{dq} = 125\text{ mA}$, $V_g = -3.6\text{ V}$ Typical
- Technology: 0.25 μm Power GaN on SiC
- Chip Dimensions: 0.82 x 0.66 x 0.10 mm

Primary Applications

- Defense & Aerospace
- Broadband Wireless

Product Description

The TriQuint TGF2023-01 is a discrete 1.25 mm GaN on SiC HEMT which operates from DC-18 GHz. The TGF2023-01 is designed using TriQuint's proven 0.25 μm GaN production process. This process features advanced field plate techniques to optimize microwave power and efficiency at high drain bias operating conditions.

The TGF2023-01 typically provides 38 dBm of saturated output power with power gain of 9.5 dB at 10GHz. The maximum power added efficiency is 55% which makes the TGF2023-01 appropriate for high efficiency applications.

Lead-free and RoHS compliant

Datasheet subject to change without notice.

Table I
Absolute Maximum Ratings 1/

Symbol	Parameter	Value	Notes
Vd	Drain Voltage	40 V	<u>2/</u>
Vg	Gate Voltage Range	-10 to 0 V	
Id	Drain Current	1.25 A	<u>2/</u>
Ig	Gate Current	7 mA	
Pin	Input Continuous Wave Power	31 dBm	<u>2/</u>
Tch	Channel Temperature	200 °C	

1/ These ratings represent the maximum operable values for this device. Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device and / or affect device lifetime. These are stress ratings only, and functional operation of the device at these conditions is not implied.

2/ Combinations of supply voltage, supply current, input power, and output power shall not exceed the maximum power dissipation listed in Table IV.

Table II
Recommended Operating Conditions

Symbol	Parameter	Value
Vd	Drain Voltage	28 - 35 V
Idq	Drain Current	125 mA
Id_Drive	Drain Current under RF Drive, Typical	400 mA
Vg	Gate Voltage, Typical	-3.6 V

Table III
RF Characterization 1/

Bias: $V_d = 30\text{ V}$, $I_{dq} = 125\text{ mA}$, $V_g = -3.6\text{ V}$ Typical, Frequency = 10 GHz

SYMBOL	PARAMETER	$V_d = 30\text{ V}$	UNITS
Power Tuned:			
Psat	Saturated Output Power	38	dBm
PAE	Power Added Efficiency	50	%
Gain	Power Gain	9.5	dB
R_p <u>2/</u>	Parallel Resistance	54.5	$\Omega \cdot \text{mm}$
C_p <u>2/</u>	Parallel Capacitance	0.376	pF/mm
Γ_L <u>3/</u>	Load Reflection Coefficient	$0.57 \angle 131$	-
Efficiency Tuned:			
Psat	Saturated Output Power	37	dBm
PAE	Power Added Efficiency	55	%
Gain	Power Gain	10	dB
R_p <u>2/</u>	Parallel Resistance	86.0	$\Omega \cdot \text{mm}$
C_p <u>2/</u>	Parallel Capacitance	0.384	pF/mm
Γ_L <u>3/</u>	Load Reflection Coefficient	$0.67 \angle 121$	-

- 1/ Values in this table are measured on a 1.25 mm GaN/SiC unit cell at 10 GHz
- 2/ Large signal equivalent output network (normalized) (see figure, pg 8)
- 3/ Optimum Γ_{Load} (Γ_L) for maximum power or maximum PAE at 10 GHz

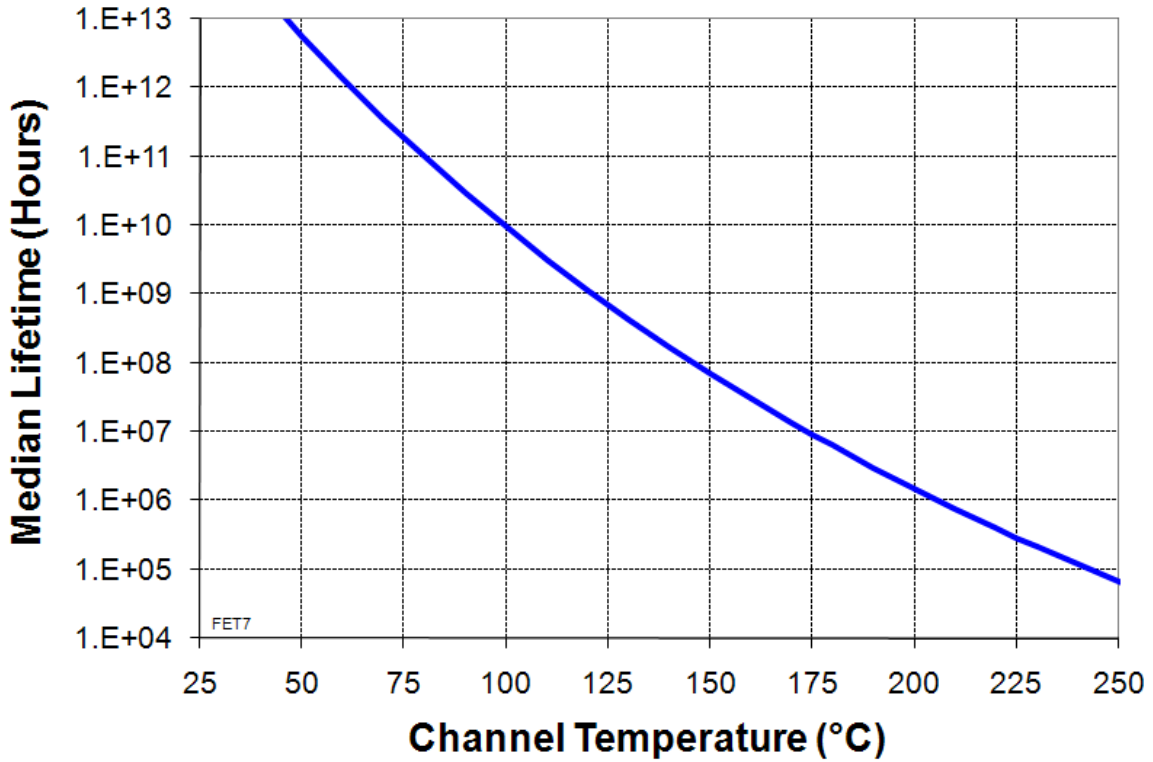
Table IV
Power Dissipation and Thermal Properties 1/

Parameter	Test Conditions	Value	Notes
Maximum Power Dissipation	Tbaseplate = 70 °C	Pd = 8.1 W Tchannel = 200 °C Tm = 1.5E+6 Hrs	<u>2/</u>
Thermal Resistance, θ_{jc}	Vd = 30 V Id = 125 mA Pd = 3.75 W Tbaseplate = 70 °C	θ_{jc} = 16.0 (°C/W) Tchannel = 130 °C Tm = 4.4E+8 Hrs	
Thermal Resistance, θ_{jc} Under RF Drive	Vd = 30 V Id = 373 mA Pout = 38 dBm Pd = 5.6 W Tbaseplate = 70 °C	θ_{jc} = 16.0 (°C/W) Tchannel = 160 °C Tm = 3.2E+7 Hrs	
Mounting Temperature	30 Seconds	320 °C	
Storage Temperature		-65 to 150 °C	

1/ Assumes eutectic attach using 1mil thick 80/20 AuSn mounted to a 10mil CuMo Carrier Plate

2/ Channel operating temperature will directly affect the device median lifetime. For maximum life, it is recommended that channel temperatures be maintained at the lowest possible levels.

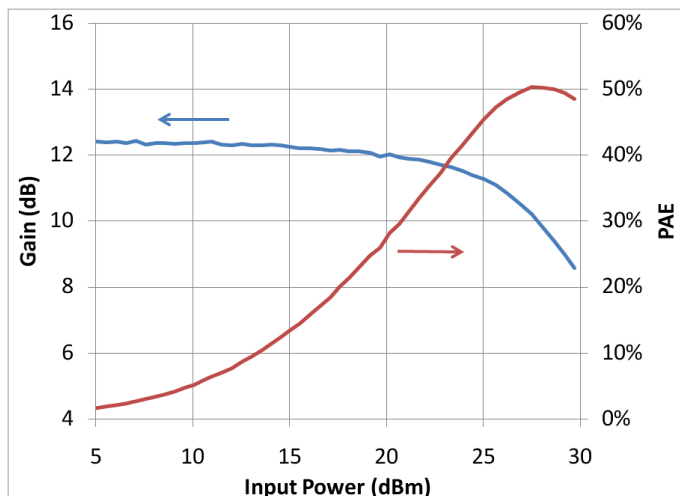
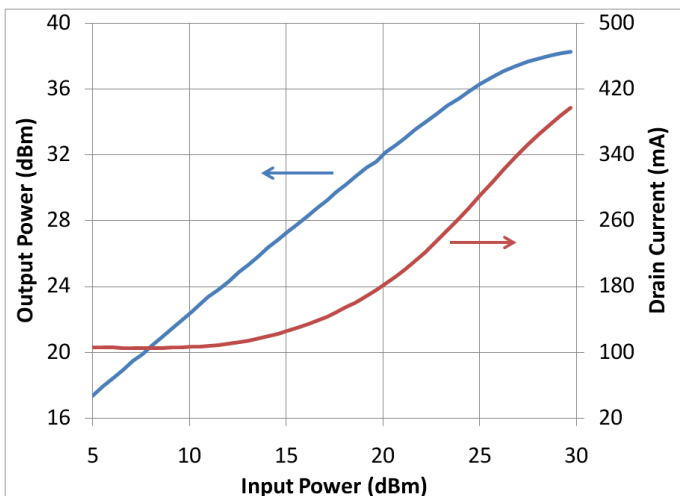
Median Lifetime vs Channel Temperature



Measured Data

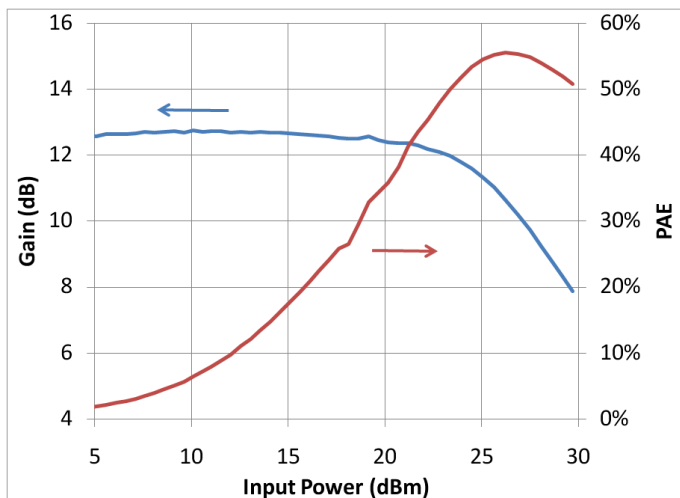
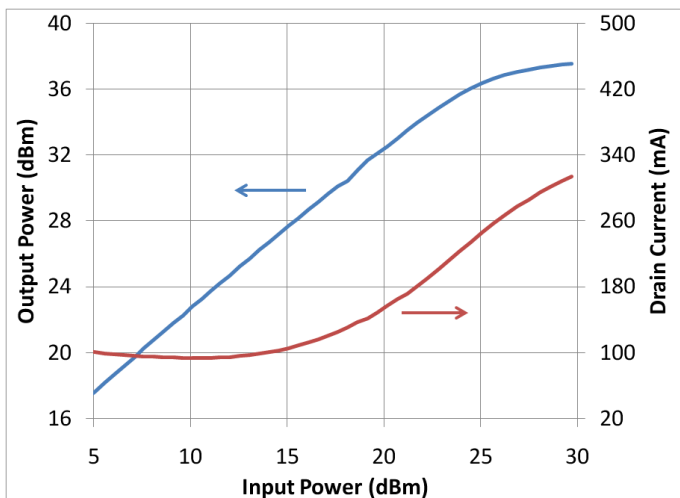
Bias conditions: $V_d = 30\text{ V}$, $I_{dQ} = 125\text{ mA}$, $V_g = -3.6\text{ V}$ Typical

Power tuned data at 10GHz



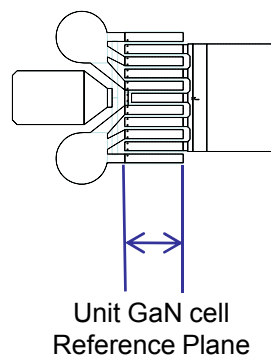
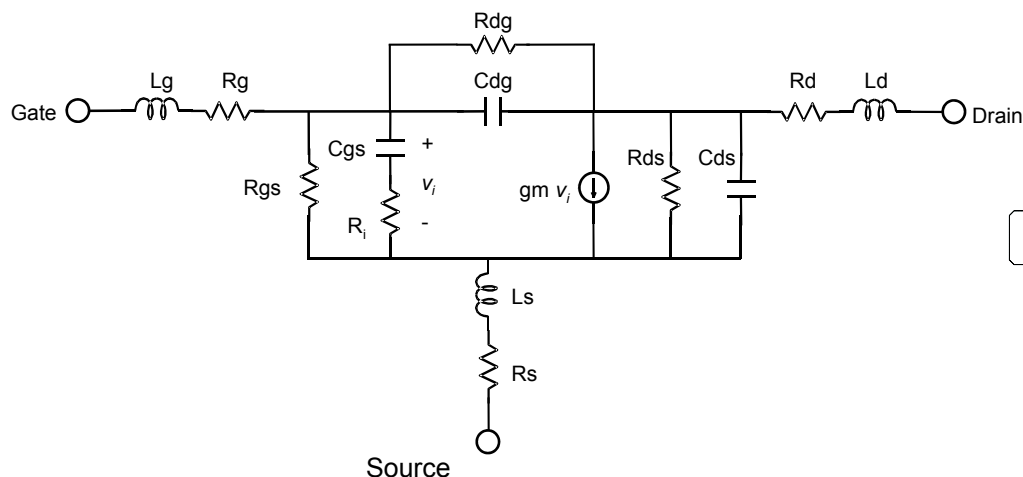
For power tuned devices at 10GHz:
1.25mm device is input matched for maximum gain & output load is:
 $V_d=30\text{V}$: $R_p = 54.5\ \Omega\text{-mm}$, $C_p = 0.376\text{ pF/mm}$, $\Gamma = 0.57$, $\theta = 130^\circ$

Efficiency tuned data at 10GHz



For efficiency tuned devices at 10GHz:
1.25mm device is input matched for maximum gain & output load is:
 $V_d=30\text{V}$: $R_p = 86.0\ \Omega\text{-mm}$, $C_p = 0.384\text{ pF/mm}$, $\Gamma = 0.67$, $\theta = 121^\circ$

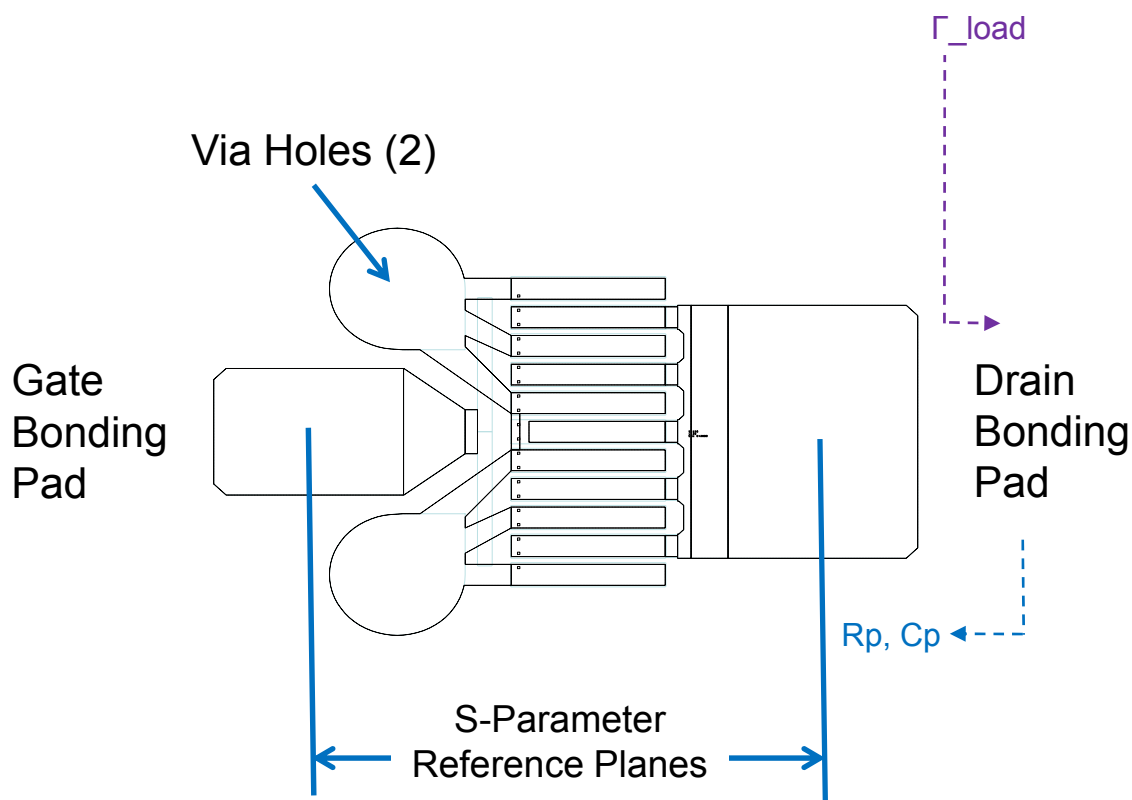
Linear Model for 1.25 mm Unit GaN Cell (UGC)



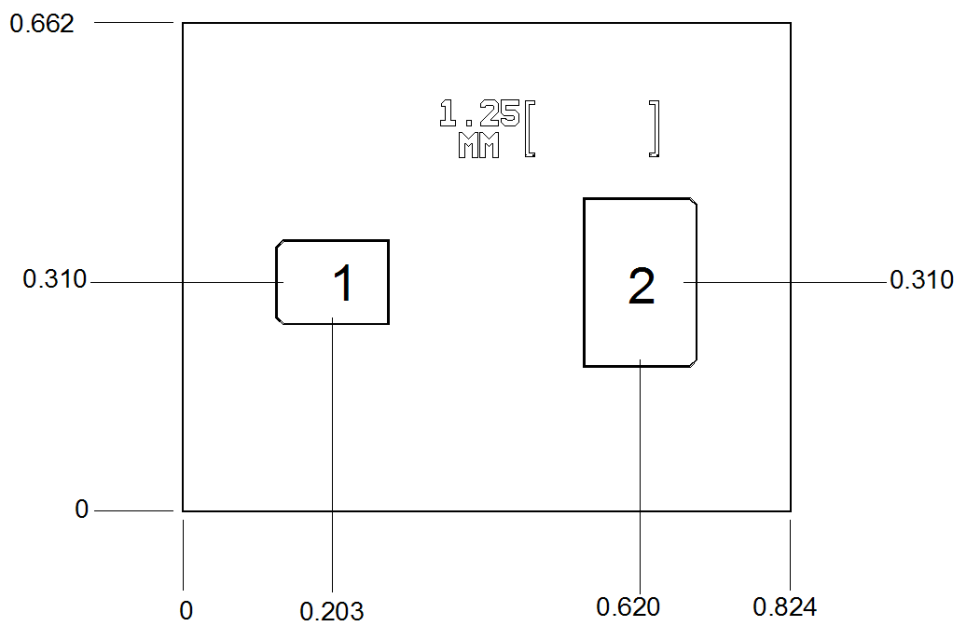
MODEL PARAMETER	Vd = 30V Idq = 125mA	UNITS
Rg	0.42	Ω
Rs	0.13	Ω
Rd	0.70	Ω
gm	0.302	S
Cgs	1.994	pF
Ri	2.62	Ω
Cds	0.275	pF
Rds	98.08	Ω
Cgd	0.068	pF
Tau	0.19	pS
Ls	-0.002	nH
Lg	-0.026	nH
Ld	-0.017	nH
Rgs	37800	Ω
Rgd	303000	Ω

Complete 1.25mm GaN HEMT Linear Model

Includes 1 UGC, 2 vias, and bonding pads



Mechanical Drawing



Units: millimeters

Thickness: 0.100

Die x,y size tolerance: +/- 0.050

Chip edge to bond pad dimensions are shown to center of pad

Ground is backside of die

Bond Pad #1	Vg	0.154 x 0.115
Bond Pad #2	Vd	0.154 x 0.230

GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.

Assembly Notes

Component placement and adhesive attachment assembly notes:

- Vacuum pencils and/or vacuum collets are the preferred method of pick up.
- Air bridges must be avoided during placement.
- The force impact is critical during auto placement.
- Organic attachment (i.e. epoxy) can be used in low-power applications.
- Curing should be done in a convection oven; proper exhaust is a safety concern.

Reflow process assembly notes:

- Use AuSn (80/20) solder and limit exposure to temperatures above 300°C to 3-4 minutes, maximum.
- An alloy station or conveyor furnace with reducing atmosphere should be used.
- Do not use any kind of flux.
- Coefficient of thermal expansion matching is critical for long-term reliability.
- Devices must be stored in a dry nitrogen atmosphere.

Interconnect process assembly notes:

- Ball bonding is the preferred interconnect technique, except where noted on the assembly diagram.
- Force, time, and ultrasonics are critical bonding parameters.
- Aluminum wire should not be used.
- Devices with small pad sizes should be bonded with 0.0007-inch wire.

Ordering Information

Part	ECCN	Package Style
TGF2023-01	EAR99	GaN on SiC Die

GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.